



DMP3025LK3



30V P-CHANNEL ENHANCEMENT MODE MOSFET

Product Summary

V _{(BR)DSS}	R _{DS(on)}	I _D T _A = 25°C		
-30V	25mΩ @ V _{GS} = -10V	-16.1A		
	41mΩ @ V _{GS} = -4.5V	-12.5A		

Description and Applications

This new generation MOSFET has been designed to minimize the onstate resistance ($R_{DS(on)}$) and yet maintain superior switching performance, making it ideal for high efficiency power management applications.

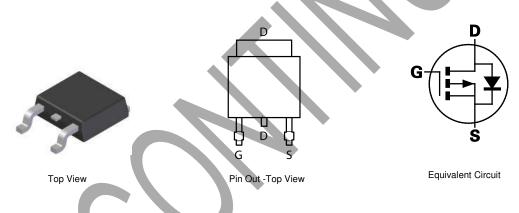
- Backlighting
- DC-DC Converters
- Power management functions

Features and Benefits

- Low on-resistance
- Fast switching speed
- "Green" component and RoHS compliant (Note 1)

Mechanical Data

- Case: TO252-3L
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0 (Note 1)
- Moisture Sensitivity: Level 1 per J-STD-020D
- Terminals Connections: See Diagram
- Terminals: Matte Tin Finish annealed over Copper leadframe. Solderable per MIL-STD-202, Method 208
- Marking Information: See Below
- Ordering Information: See Below
- Weight: 0.33 grams (approximate)

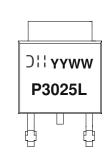


Ordering Information (Note 1)

Product	Marking	Reel size (inches)	Tape width (mm)	Quantity per reel
DMP3025LK3-13	P3025L	13	16	2,500

Note: 1. Diodes, Inc. defines "Green" products as those which are Eu RoHS compliant and contain no halogens or antimony compounds; further information about Diodes Inc.'s "Green" Policy can be found on our website. For packaging details, go to our website.

Marking Information



)'' = Manufacturer's Marking
P3025L = Product Type Marking Code
YYWW = Date Code Marking
YY = Year (ex: 09 = 2009)
WW = Week (01-52)





Maximum Ratings @T_A = 25°C unless otherwise specified

Characteristic			Symbol	Value	Unit	
Drain-Source voltage			V _{DSS}	-30	V	
Gate-Source voltage	iate-Source voltage			±20	V	
		(Note 3)	Ι _D	-16.1		
Continuous Drain current	$V_{GS} = 10V$	T _A =70°C (Note 3)		-12.9	А	
		(Note 2)		-10.6		
Pulsed Drain current	V _{GS} = 10V	(Note 4)	I _{DM}	-41.9	A	
Continuous Source current (Body diode)	(Note 3)	Is	-12.6	A	
Pulsed Source current (Body diode) (Note 4)		I _{SM}	-41.9	А		

Thermal Characteristics @TA = 25°C unless otherwise specified

Characteristic	Symbol	Value	Unit	
	(Note 2)		4.3 34.5	*
Power dissipation Linear derating factor	(Note 3)	PD	10.0 80.0	W mW/°C
	(Note 5)		2.15 17.2	
	(Note 2)		29.0	
Thermal Resistance, Junction to Ambient	(Note 3)	R ₀ JA	12.5	2011
	(Note 5)		58.0	°C/W
Thermal Resistance, Junction to Lead	(Note 6)	$R_{ extsf{ heta}JL}$	1.02	
Operating and storage temperature range		TJ, TSTG	-55 to 150	°C

2. For a device surface mounted on 50mm x 50mm x 1.6mm FR4 PCB with high coverage of single sided 2oz copper, in still air conditions; the device is measured when operating in a steady-state condition. Notes:

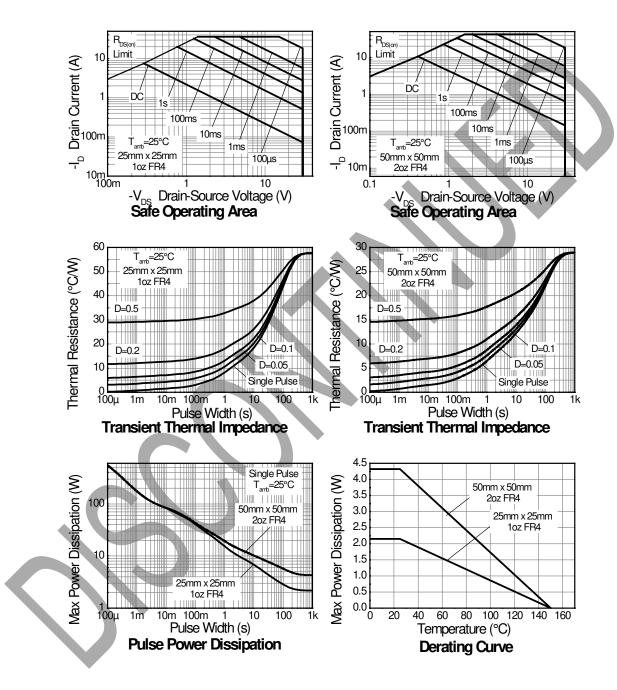
3. Same as note 2, except the device is pulsed with D = 0.02 and pulse width 300 µs. The pulse current is limited by the maximum junction temperature. 5. For a device surface mounted on 25mm x 25mm x 1.6mm FR4 PCB with high coverage of single sided 1oz copper, in still air conditions; the device is

- measured when operating in a steady-state condition.
- 6. Thermal resistance from junction to solder-point (at the end of the drain lead).





Thermal Characteristics







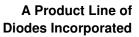
DMP3025LK3

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition		
OFF CHARACTERISTICS					•			
Drain-Source Breakdown Voltage	BV _{DSS}	-30			V	$I_D = -250 \mu A, V_{GS} = 0 V$		
Zero Gate Voltage Drain Current	I _{DSS}	_		-0.5	μA	V _{DS} = -30V, V _{GS} = 0V		
Gate-Source Leakage	I _{GSS}	_		±100	nA	V_{GS} = ±20V, V_{DS} = 0V		
ON CHARACTERISTICS								
Gate Threshold Voltage	V _{GS(th)}	-1.0		-3.0	V	I_D = -250µA, V_{DS} = V_{GS}		
Static Drain-Source On-Resistance (Note 7)	R _{DS (ON)}			0.025	•	V _{GS} = -10V, I _D = -7.1A		
	TUDS (ON)			0.041		V_{GS} = -4.5V, I_{D} = -5.5A		
Forward Transconductance (Notes 7 & 8)	g fs	_	18.6	_	S	V_{DS} = -15V, I_{D} = -7.1A		
Diode Forward Voltage (Note 7)	V _{SD}	—	-0.80	-1.2	V	I _S = -1.7A, V _{GS} = 0V		
Reverse recovery time (Note 8)	t _{rr}		16.2	_	ns			
Reverse recovery charge (Note 8)	Q _{rr}	—	10	_	nC	–1 _S = -2.2A, di/dt= 100A/μs		
DYNAMIC CHARACTERISTICS (Note 8)								
Input Capacitance	C _{iss}	—	1678	—	pF			
Output Capacitance	C _{oss}	—	303		рF	−V _{DS} = -15V, V _{GS} = 0V -f= 1MHz		
Reverse Transfer Capacitance	C _{rss}	_	178	-	pF	1- 110112		
Total Gate Charge	Qg		16.5		nC	V _{GS} = -4.5V		
Total Gate Charge	Qg		31.6	—	nC	V _{DS} = -15V,		
Gate-Source Charge	Q _{gs}		4.3		nC	V _{GS} = -10V I _D = -7.1A		
Gate-Drain Charge	Q _{gd}	_	6.2		nC			
Turn-On Delay Time (Note 9)	t _{D(on)}	—	3.5		ns			
Turn-On Rise Time (Note 9)	tr	—	4.9		ns	V _{DD} = -15V, V _{GS} = -10V		
Turn-Off Delay Time (Note 9)	t _D (off)		44		ns	$I_{D}\text{=-1A, }R_{G}\cong 6.0\Omega$		
Turn-Off Fall Time (Note 9)	tf		23		ns	7		

Notes:

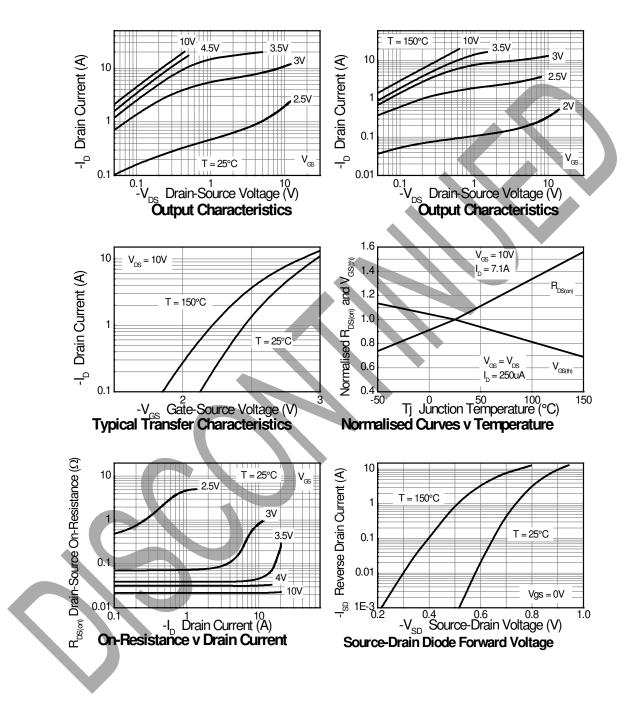
Measured under pulsed conditions. Pulse width ≤ 300µs; duty cycle ≤ 2%
 For design aid only, not subject to production testing.
 Switching characteristics are independent of operating junction temperatures.



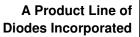




Typical Characteristics

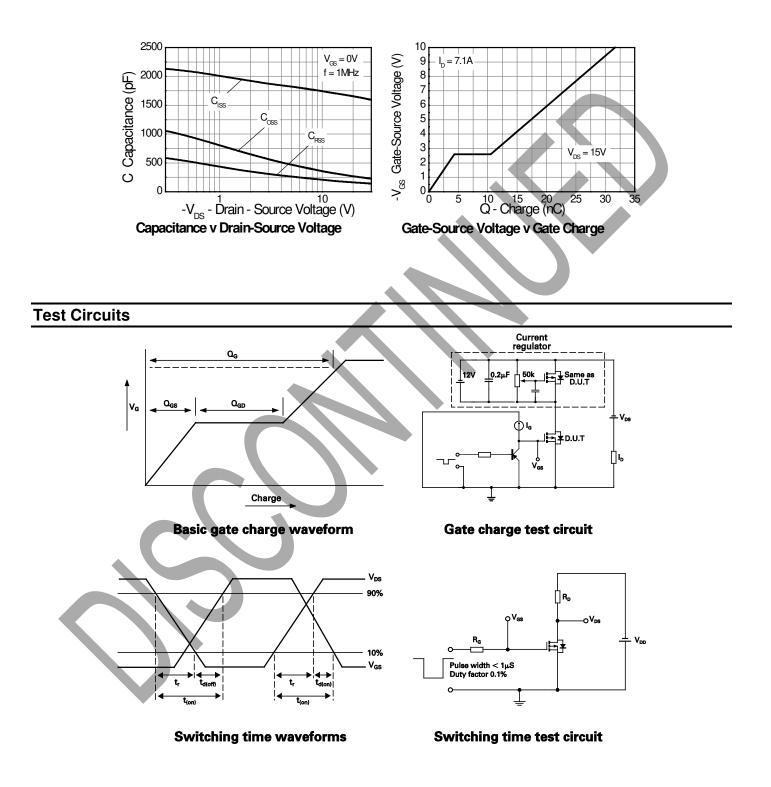






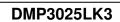


Typical Characteristics - continued

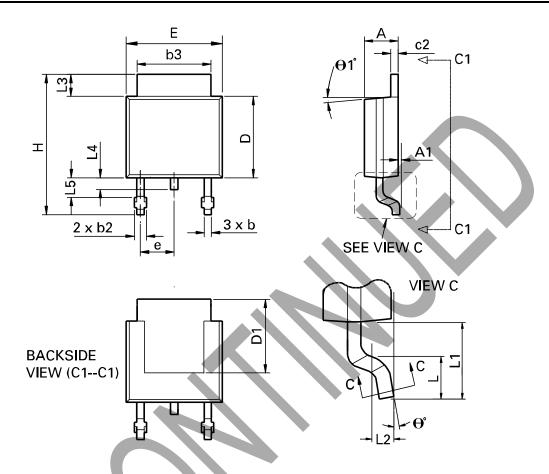






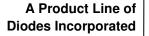


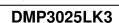
Package Outline Dimensions



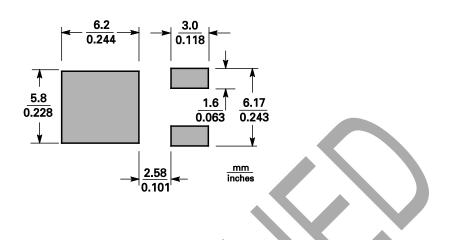
DIM	Inc	hes	Millimeters		DIM	Inches		Millimeters	
	Min	Мах	Min	Мах		Min	Max	Min	Max
А	0.086	0.094	2.18	2.39	е	0.090 BSC		2.29 BSC	
A1	-	0.005	-	0.127	н	0.370	0.410	9.40	10.41
b	0.020	0.035	0.508	0.89	L	0.055	0.070	1.40	1.78
b2	0.030	0.045	0.762	1.14	L1	0.108 REF		2.74 REF	
b3	0.205	0.215	5.21	5.46	L2	0.020 BSC		0.508 BSC	
c	0.018	0.024	0.457	0.61	L3	0.035	0.065	0.89	1.65
c2	0.018	0.023	0.457	0.584	L4	0.025	0.040	0.635	1.016
D	0.213	0.245	5.41	6.22	L5	0.045	0.060	1.14	1.52
D1	0.205	-	5.21	-	• 1°	0°	10°	0°	10°
Е	0.250	0.265	6.35	6.73	• °	0°	15°	0°	15°
E1	0.170	-	4.32	-	-	-	-	-	-







Suggested Pad Layout



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